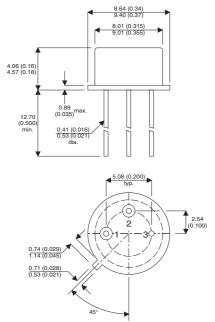


2N6794





N–CHANNEL ENHANCEMENT MODE POWER MOSFET

| BV_{DSS} | 500V |
|----------------------|--------------|
| I _{D(cont)} | 1.5 |
| R _{DS(on)} | 3.0 Ω |

FEATURES

- AVALANCHE ENERGY RATED
- HERMETICALLY SEALED
- DYNAMIC dv/dt RATING
- SIMPLE DRIVE REQUIREMENTS

Underside View Pin 1 – Source Pin 2 – Gate Pin 3 – Drain

TO39 – Package (TO-205AF)

ABSOLUTE MAXIMUM RATINGS (T_{case} = 25°C unless otherwise stated)

| V _{GS} | Gate – Source Voltage | ±20V | | |
|-----------------------------------|--|--------------|--|--|
| I _D | Continuous Drain Current $(V_{GS} = 10V, T_{case} = 25^{\circ}C)$ | 1.5A | | |
| I _D | Continuous Drain Current $(V_{GS} = 10V, T_{case} = 100^{\circ}C)$ | 1A | | |
| I _{DM} | Pulsed Drain Current ¹ | 6.5A | | |
| P _D | Power Dissipation @ T _{case} = 25°C | 20W | | |
| | Linear Derating Factor | 0.16W/°C | | |
| E _{AS} | Single Pulse Avalanche Energy ² | 0.11mJ | | |
| dv/dt | Peak Diode Recovery ³ | 3.5V/ns | | |
| T _J , T _{stg} | Operating and Storage Temperature Range | –55 to 150°C | | |
| $R_{\theta JC}$ | Thermal Resistance Junction to Case | 6.25°C/W | | |
| $R_{	extsf{	heta}JA}$ | Thermal Resistance Junction-to-Ambient | 175°C/W | | |
| | | | | |

Notes

1) Pulse Test: Pulse Width \leq 300 μ s, $\delta \leq$ 2%

2) @ V_DD = 50V , L \geq 0.100mH , R_G = 25 Ω , Peak I_L = 1.5A , Starting T_J = 25°C

3) @ I_{SD} \leq 1.5A , di/dt \leq 50A/ μs , V_{DD} \leq BV_{DSS} , T_J \leq 150°C , SUGGESTED R_G = 7.5 Ω

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ELECTRICAL CHARACTERISTICS (Tamb = 25°C unless otherwise stated)

| | Parameter | Test Conditions | | Min. | Тур. | Max. | Unit |
|---------------------|--|--|-------------------------|------|------------|------|-------|
| | STATIC ELECTRICAL RATINGS | 1 | | 1 | | | 1 |
| BV _{DSS} | Drain – Source Breakdown Voltage | $V_{GS} = 0$ | I _D = 1mA | 500 | | | V |
| ΔBV_{DSS} | Temperature Coefficient of | Reference to 25°C | | | | | 1/100 |
| ΔT_{J} | Breakdown Voltage | I _D = 1mA | | | 0.43 | | V/°C |
| R _{DS(on)} | Static Drain – Source On–State | $V_{GS} = 10V$ | I _D = 1A | | | 3 | |
| | Resistance | $V_{GS} = 10V$ | I _D = 1.5A | | | 3.45 | Ω |
| V _{GS(th)} | Gate Threshold Voltage | $V_{DS} = V_{GS}$ | I _D = 250μA | 2 | | 4 | V |
| 9 _{fs} | Forward Transconductance | V _{DS} =5V | I _{DS} = 1A | 1 | | 3 | S(ଫ) |
| | Zero Gate Voltage Drain Current | $V_{GS} = 0$ | $V_{DS} = 0.8BV_{DSS}$ | | | 25 | μΑ |
| IDSS | | | T _J = 125°C | | | 250 | |
| I _{GSS} | Forward Gate - Source Leakage | $V_{GS} = 20V$ | | | | 100 | - n A |
| I _{GSS} | Reverse Gate – Source Leakage | $V_{GS} = -20V$ | | | | -100 | nA |
| | DYNAMIC CHARACTERISTICS | 1 | | | | | |
| C _{iss} | Input Capacitance | $V_{GS} = 0$ | | | 350 | | |
| C _{oss} | Output Capacitance | V _{DS} = 25V | | | 80 | | pF |
| C _{rss} | Reverse Transfer Capacitance | f = 1MHz | - | | 35 | | |
| | | V _{GS} = 10V | I _D = 1.5A | 7.0 | | 167 | |
| Qg | Total Gate Charge | $V_{DS} = 0.5 BV_{DS}$ | | 7.3 | | 16.7 | nC |
| Q _{gs} | Gate – Source Charge | I _D =1.5A | | 0.1 | | 3 | nC |
| Q _{gd} | Gate – Drain ("Miller") Charge | $V_{DS} = 0.5BV_{DS}$ | | 3.7 | | 8.7 | |
| t _{d(on)} | Turn–On Delay Time | V 050V | | | 4 | 40 | - ns |
| t _r | Rise Time | $V_{DD} = 250V$ | | | | 30 | |
| t _{d(off)} | Turn–Off Delay Time | $I_{\rm D} = 1.5A$ | | | | 60 | |
| t _f | Fall Time | - R _G = 7.5Ω | - | | | 30 | |
| | SOURCE - DRAIN DIODE CHARAC | TERISTICS | | | | | |
| I _S | Continuous Source Current | | | | | 1.5 | |
| I _{SM} | Pulse Source Current ² | | | | | 6.5 | - A |
| | | I _S = 1.5A | $T_J = 25^{\circ}C$ | | | 1.0 | V |
| | Diode Forward Voltage | $V_{GS} = 0$ | - | | | 1.2 | |
| t _{rr} | Reverse Recovery Time | I _F = 1.5A | T _J = 25°C | | | 900 | ns |
| Q _{rr} | Reverse Recovery Charge | [−] d _i / d _t ≤ 100A/µs | s V _{DD} ≤ 50V | | | 5.9 | μC |
| t _{on} | Forward Turn–On Time | | | | Negligible | | |
| - | PACKAGE CHARACTERISTICS | 1 | I | | | | 1 |
| L _D | Internal Drain Inductance (from centre o | f drain pad to die) | | 5.0 | | | |
| L _S | Internal Source Inductance (from centre | re of source pad to end of source bond wire) 15.0 | | | | | – nH |
| Notes | 1) Pulse Test: Pulse Width \leq 3 | | | | | 1 | |

2) Repetitive Rating - Pulse width limited by maximum junction temperature.

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